

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.25974	100.0	3.9
			Subtotal	0.25974	100	3.9
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.02286	10.0	0.34324
	Silver alloy	Silver (Ag)	7440-22-4	0.00457	2.0	0.06865
	Lead alloy	Lead (Pb)	7439-92-1	0.20117	88.0	3.0205
			Subtotal	0.2286	100	3.43239
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.05148	100.0	0.77295
			Subtotal	0.05148	100	0.77295
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00979	0.03	0.14694
	Pure metal layer	Zinc (Zn)	7440-66-6	0.00652	0.02	0.09796
	Pure metal layer	Tin (Sn)	7440-31-5	0.00979	0.03	0.14694
	Pure metal layer	Iron (Fe)	7439-89-6	0.03588	0.11	0.53877
	Pure metal layer	Copper (Cu)	7440-50-8	32.55802	99.81	488.8594
			Subtotal	32.62	100	489.79001
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.34412	100.0	5.167
			Subtotal	0.34412	100	5.167
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	5.31969	8.0	79.8752
	Filler	Silica fused	60676-86-0	53.86181	81.0	808.7364
	Metal hydroxide	Metal hydroxide		0.46547	0.7	6.98908
	Carbon Black	Carbon black	1333-86-4	0.19949	0.3	2.99532
	Polymer	Epoxy resin system		6.64961	10.0	99.844
			Subtotal	66.49607	100	998.44
			Total	100.00001	100	1501.50235

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.